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XIE et al.(54) **PREPARATION METHOD FOR CONNECTOR
ELECTRONIC DEVICE CONNECTOR AND
APPLICATION THEREOF**(52) **U.S. CL.**
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Shenzhen (CN)(57) **ABSTRACT**(21) Appl. No.: **17/411,628**(22) Filed: **Aug. 25, 2021**(30) **Foreign Application Priority Data**

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An electronic device, comprising: a first functional board, a second functional board, and a connector main body, wherein the connector main body is a PCB, wherein a plurality of via holes are formed in the PCB, wherein soldering pads are arranged in the via holes, and wherein the soldering pads are used for communicating the first functional board and second functional board, wherein the PCB is provided with a space for accommodating elements on the first and second functional boards, wherein the soldering pads on both sides of the connector are respectively connected with the soldering pad of the first functional board and the soldering pad of the second functional board.

S100: preparing a PCB (Printed Circuit Board) having a shape matched with the shape and structure of functional boards needing to be connected, and forming via holes in the PCB, wherein the via holes correspond to the positions of soldering pads of the functional boards;

S200: preparing soldering pads for connecting the functional boards on the PCB, wherein the soldering pads are arranged in the via holes for communicating the functional boards on both sides of the PCB.